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# MuAnalysis

*Leaders in diagnostic services for microelectronics and photonics*

## **Nitronex NPT35015 GaN HEMT Teardown and Technology Analysis**

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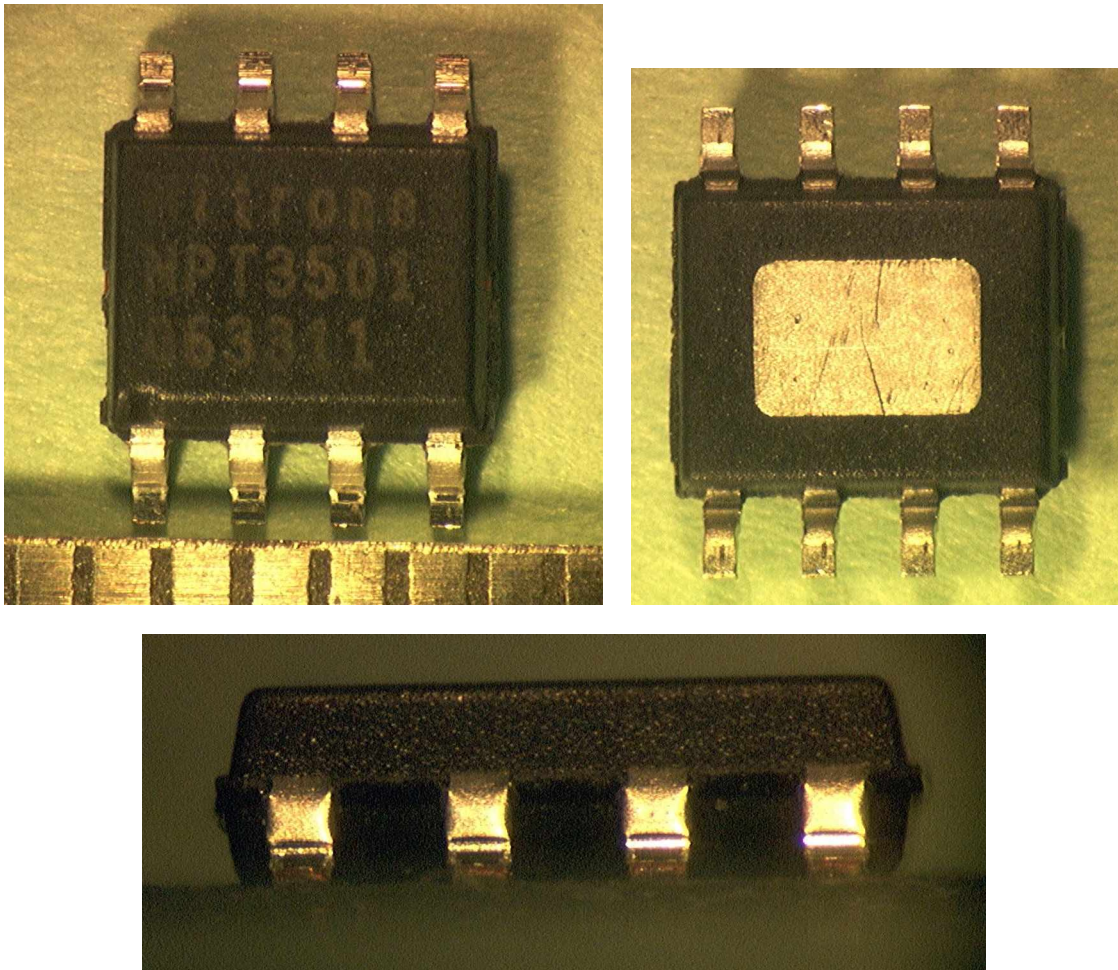
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## 1. Product Identification

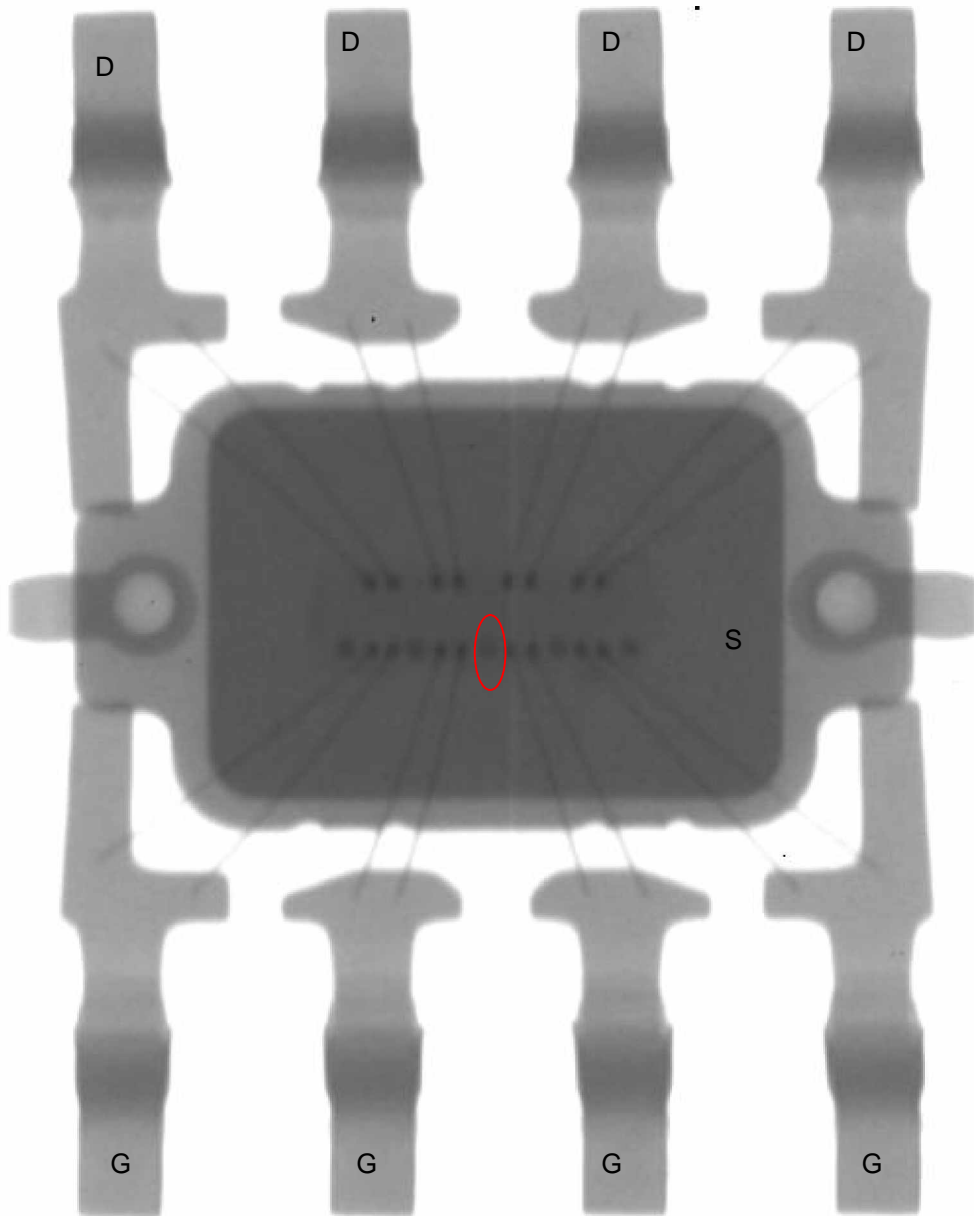
Manufacturer	Device ID	Date/lot code
Nitronex	NPT35015	063311

## 2. External Appearance and Principal Dimensions



*Figure 2.1: Devices as received. The markings of the ruler are 1mm apart.*

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*Figure 2.2: Plan view XRAY. Wire bonds connect the gate and drain to the leg pins. The source contact is under the device. There are 5 through wafer vias visible, one is circled in red.*

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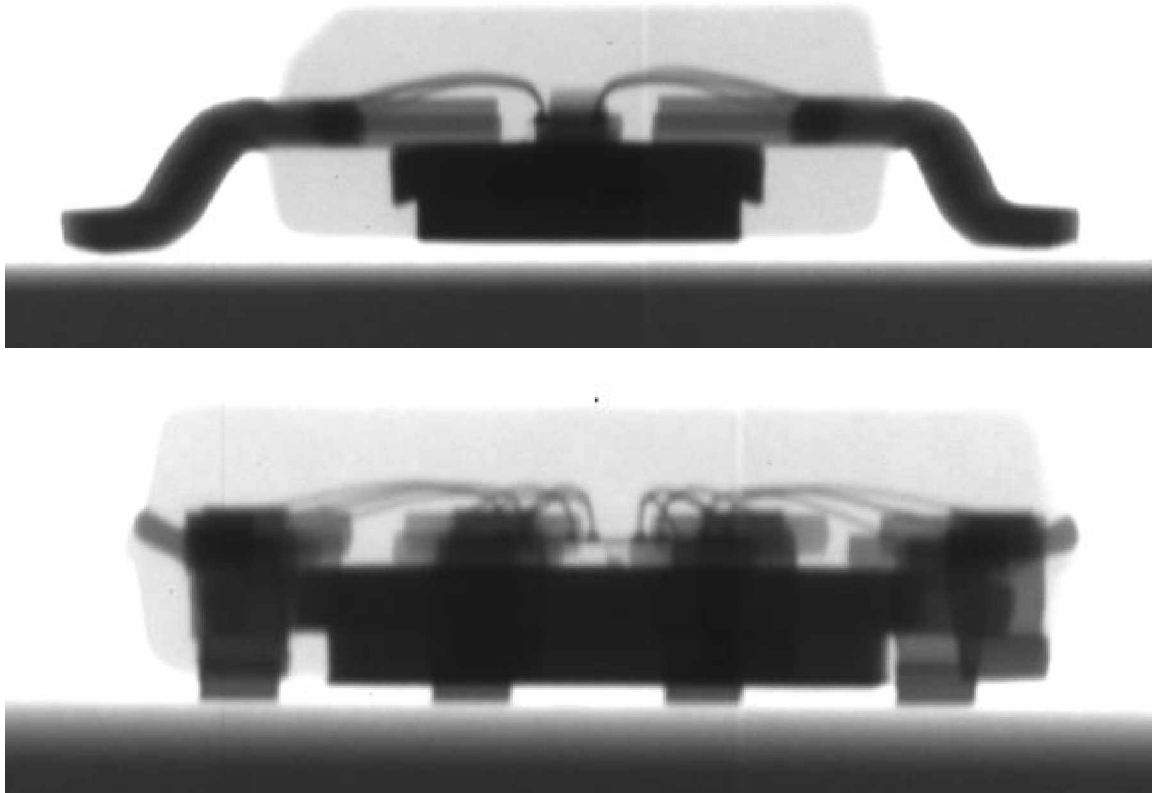


Figure 2.3: Elevation view XRAYs.

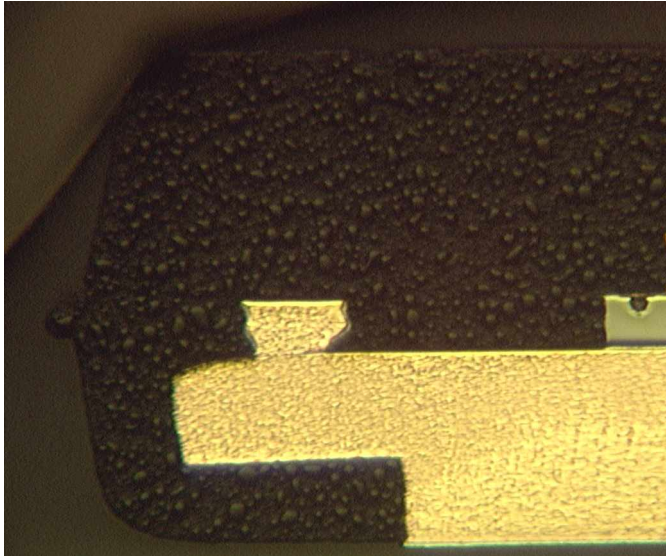
Table 2.1 Data sheet and measured external dimensions (mm.)

Dimension	Data Sheet Value	Measured
Body width	3.81-3.99	3.78
Body length	4.80-4.98	5.12
Body thickness	1.40-1.55	1.49
Lead width	0.35-0.49	0.42
Lead pitch	1.27	1.27

Note: the data sheet values are in inches, though the table indicates mm. The inches table is not filled. We have done the conversion.

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### 3. Package Construction and Materials



*Figure 3.1: Cross-section of the package showing the die on the heat spreader. The cross-section is through the gate and source bond pads, just entering the through wafer vias.*

To purchase the full report, or to request further analyses on this product, please contact [sales@muanalysis.com](mailto:sales@muanalysis.com) or call 1-613-721-4664

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